

<b>Notice of References Cited</b>		Application No.		Applicant(s)	
		09/828,431		Cornett et al.	
		Examiner		Group Art Unit	
		Barbara Summers		2817	
				Pag 1.1	
U.S. PATENT DOCUMENTS					
*	DOCUMENT NO.	DATE	NAME	CLASS	SUBCLASS
A	3,490,056	1/1970	Warren et al.	333	186
B	3,614,678	10/1971	Engeler et al.	333	187
C	3,634,787	1/1972	Neigel	333	186
D	6,118,164	9/2000	Seefeldt et al.	257	417
E	6,249,073	6/2001	Nguyen et al.	310	309
F	6,489,864	12/2002	Frey et al.	333	197
G					
H					
I					
J					
K					
L					
M					
FOREIGN PATENT DOCUMENTS					
*	DOCUMENT NO.	DATE	COUNTRY	NAME	CLASS
N					
O					
P					
Q					
R					
S					
T					
NON-PATENT DOCUMENTS					
*	DOCUMENT (Including Author, Title, Source, and Pertinent Pages)				DATE
U					
V					
W					
X					

\* A copy of this reference is not being furnished with this Office action.  
(See Manual of Patent Examining Procedure, Section 707.05(a).)



Form PTO-1449 U.S. Dept. of Commerce, Patent and Trademarks							
LIST OF ART CITED BY APPLICANT (Use several sheets if necessary)							
Attorney Docket No. CM03351J		Serial No. 09/828,431		Filing Date 4/9/01			
Applicant: Kenneth D. Cornett			Group 2817				
U.S. PATENT DOCUMENTS							
Examiner's Initial		Document No.	Date	Name	Class	Subclass	
	AA						
	AB						
	AC						
	AD						
	AE						
	AF						
	AG						
	AH						
FOREIGN PATENT DOCUMENTS							
		Document No.	Date	Country	Class	Subclass	Translation Yes or No
B8	AI	EP 1045 448 A1	10/18/200	EPO			
	AJ						
	AK						
OTHER PRIOR ART (Including Author Title, Date, Pertinent Pages, etc.)							
B8	AL	Wang, Kun et al. VHF Free-Free Beam High Q Micromechanical Resonators. Technical Digest, 12th International IEEE Micro Electro Mechanical System Conference, Orlando, Florida Jan 17-21, 1999, pp 453-458.					
B8	AM	Wang, Kun et al. VHF Free-Free Beam High Q Micromechanical Resonators. Journal of Microelectromechanical Systems, Vol 9, No. 3 (September 2000), pp 347-359.					
B8	AN	Ayazi, Farrokh et al. High Aspect-Ratio Combined Poly and Single-Crystal Silicon (HARPSS) MEMSS Technology. Journal of Microelectromechanical Systems, Vol. 9, No. 3 (September 2000), pp 288-294.					
EXAMINER Bailau Summons				DATE CONSIDERED: 5/8/03			
EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance. Include copy of this form with next communication to Applicant.							

# 2

Form PTO-1449 U.S. Dept. of Commerce, Patent and Trademarks							
LIST OF ART CITED BY APPLICANT							
(Use several sheets if necessary)							
Attorney Docket No. CM03351J		Serial No. 09/828,431		Filing Date 4/9/01			
Applicant: Kenneth D. Cornett			Group 2017				
U.S. PATENT DOCUMENTS							
Examiner's Initial		Document No.	Date	Name	Class	Subclass	
	AA						
	AB						
	AC						
	AD						
	AE						
	AF						
	AG						
	AH						
FOREIGN PATENT DOCUMENTS							
		Document No.	Date	Country	Class	Subclass	Translation Yes or No
	AI						
	AJ						
	AK						
OTHER PRIOR ART (Including Author Title, Date, Pertinent Pages, etc.)							
BB	AL	Web page entitled "New Developments in Canon ELTRAN SOI Wafer Technology," <a href="http://www.usa.canon.com/indtech/semicondeq/news_developments.html">http://www.usa.canon.com/indtech/semicondeq/news_developments.html</a> , printed 3/21/01 (6 pages).					
BB	AM	Flandre, Denis, Colinge, Jean Pierre, Status and Trends of SOI, <a href="http://www.dice.ucl.ac.be/%7EFlandre/ESSCIRC94/ESSCIRC94.html">http://www.dice.ucl.ac.be/%7EFlandre/ESSCIRC94/ESSCIRC94.html</a> , printed 2/21/01 (11 pages).					
BB	AN	Goselle, U. Tong, Q.Y., Science and Technology of Semiconductor Wafer Bonding (Tentative), Chapter 7, <a href="http://www.duke.edu/web/wblch7/ch7-hpge.html">http://www.duke.edu/web/wblch7/ch7-hpge.html</a> , printed 3/20/01 (28 pages) [Table of Contents, 11 pages].					
EXAMINER Paulina Summerson				DATE CONSIDERED: 5/8/03			
EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance. Include copy of this form with next communication to Applicant.							